

# FCX1051A **SOT89 NPN medium power transistor**

### Summary

 $BV_{CEO} > 40V$ 

 $I_{C(cont)} = 3A$ 

V<sub>CE(sat)</sub> < 120mV @ 1A

 $R_{CE(sat)} = 57 m\Omega$ 

 $P_D = 2W$ 

Complimentary type - FCX1151A

## **Description**

An NPN low voltage, high gain bipolar transistor offering very low saturation voltage and excellent current handling in the SOT89 package.

### **Features**

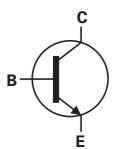
- · Very low saturation voltage
- · High gain
- Small outline package

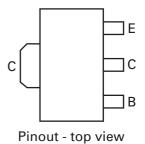
### **Applications**

- · Motor drive
- · Strobe flash
- · MOSFET and IGBT gate driving
- DC -DC converters

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
FCX1051ATA	7	12	1,000







**Device mark** 

051

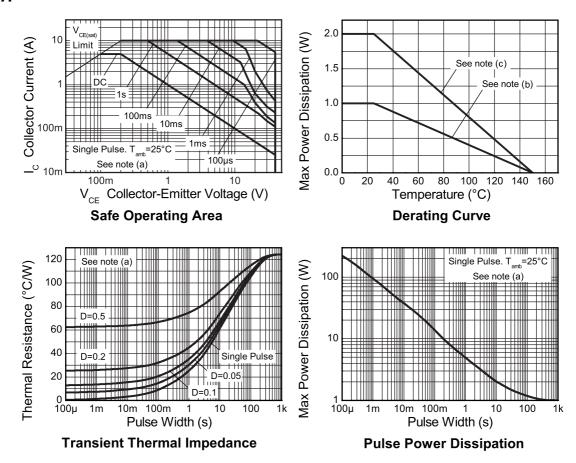
## **Absolute maximum ratings**

Parameter	Symbol	Value	Unit
Collector-base voltage	V <sub>CBO</sub>	150	V
Collector-emitter voltage	V <sub>CEO</sub>	40	V
Emitter-base voltage	V <sub>EBO</sub>	5	V
Peak pulse current <sup>(a)</sup>	I <sub>CM</sub>	10	А
Continuous collector current	I <sub>C</sub>	3	А
Power dissipation at T <sub>amb</sub> = 25°C	P <sub>tot</sub>	1 <sup>(b)</sup>	W
		2 <sup>(c)</sup>	W
Operating and storage temperature range	T <sub>j</sub> ;T <sub>stg</sub>	-55 to +150	°C

### NOTES:

- (a) Measured under pulsed conditions. Pulse width=300µs. Duty cycle ≤2%. Spice parameter data is available upon request for these devices. Refer to the handling instructions for soldering surface mount components.
- (b) Recommended  $P_{tot}$  calculated using FR4 measuring 15x15x0.6mm.
- (c) Maximum power dissipation is calculated assuming that the device is mounted on FR4 substrate measuring 40x40x0.6mm and using comparable measurement methods adopted by other suppliers.

## **Typical characteristics**



# **Electrical characteristics** (@ $T_{amb} = 25$ °C unless otherwise stated)

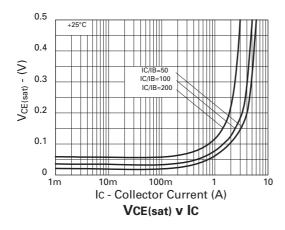
Parameter	Symbol	Min.	Тур.	Мах.	Unit	Conditions
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	150			V	I <sub>C</sub> = 100μA
Collector-emitter breakdown voltage	V <sub>CES</sub>	150			V	I <sub>C</sub> = 100μA
Collector-emitter breakdown voltage	V <sub>CEO</sub>	40			V	I <sub>C</sub> = 10mA
Collector-emitter breakdown voltage	V <sub>CEV</sub>	150			V	$I_C = 100 \mu A, V_{EB} = 1 V$
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	5			V	I <sub>E</sub> = 100μA
Collector cut-off current	I <sub>CBO</sub>		0.3	10	nA	V <sub>CB</sub> = 120V
Emitter cut-off current	I <sub>EBO</sub>		0.3	10	nA	V <sub>EB</sub> = 4V
Collector emitter cut- off current	I <sub>CES</sub>		0.3	10	nA	V <sub>CES</sub> = 120V
Collector-emitter	V <sub>CE(sat)</sub>		17	25	mV	I <sub>C</sub> = 0.2A, I <sub>B</sub> = 10mA <sup>(*)</sup>
saturation voltage			85	120	mV	I <sub>C</sub> = 1A, I <sub>B</sub> = 10mA <sup>(*)</sup>
			140	180	mV	I <sub>C</sub> = 2A, I <sub>B</sub> = 20mA <sup>(*)</sup>
			170	250	mV	I <sub>C</sub> = 3A, I <sub>B</sub> = 40mA <sup>(*)</sup>
			250	340	mV	I <sub>C</sub> = 5A, I <sub>B</sub> = 100mA <sup>(*)</sup>
Base-emitter saturation voltage	V <sub>BE(sat)</sub>		880	1000	mV	I <sub>C</sub> = 3A, I <sub>B</sub> = 40mA <sup>(*)</sup>
Base-emitter turn-on voltage	V <sub>BE(on)</sub>		840	950	mV	$I_C = 3A$ , $V_{CE} = 2V^{(*)}$
Static forward current	h <sub>FE</sub>	290	440	1200		I <sub>C</sub> = 10mA, V <sub>CE</sub> = 2V <sup>(*)</sup>
transfer ratio		270	450			$I_C = 1A$ , $V_{CE} = 2V^{(*)}$
		270	360			$I_C = 3A$ , $V_{CE} = 2V^{(*)}$
		130	220			I <sub>C</sub> = 5A, V <sub>CE</sub> = 2V <sup>(*)</sup>
		40	55			I <sub>C</sub> = 10A, V <sub>CE</sub> = 2V <sup>(*)</sup>
Transition frequency	f <sub>T</sub>		155		MHz	I <sub>C</sub> = 50mA, V <sub>CE</sub> = 10V f = 100MHz
Output capacitance	C <sub>obo</sub>		27	40	pF	V <sub>CB</sub> = 10V, f = 1MHz
Switching times	t <sub>on</sub>		220		ns	$I_C = 3A$ , $I_B = 30mA$ , $V_{CC} = 10V$
	t <sub>off</sub>		540		ns	$I_C = 3A$ , $I_B = 30mA$ , $V_{CC} = 10V$

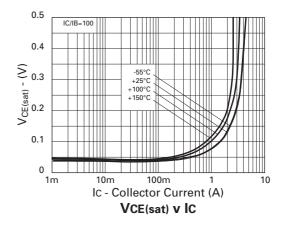
### NOTES:

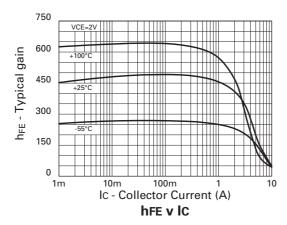
<sup>(\*)</sup> Measured under pulsed conditions. Pulse width=300 $\mu$ s. Duty cycle  $\leq\!2\%$ .

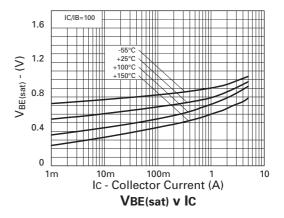
# FCX1051A

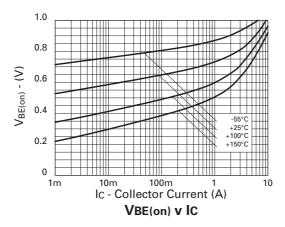
# **Typical characteristics**





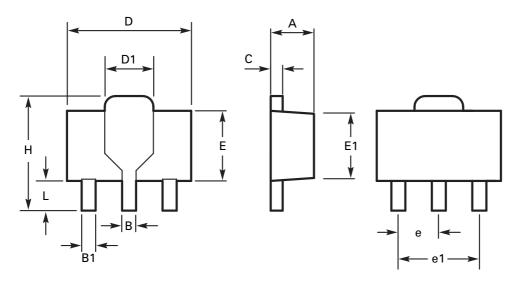






# FCX1051A

# Package outline - SOT89



DIM	Millin	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	1.40	1.60	0.550	0.630	Е	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50	BSC	0.059	BSC
С	0.35	0.44	0.014	0.017	e1	3.00	BSC	0.118	BSC
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.52	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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